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PATENT NUMBER and
ISSUE DATE

U.S. UTILITY Patent Application

APPL NUM	FILING DATE	CLASS	SUBCLASS	GAU	EXAMINER
10043863	01/10/2002	438	694	1765	C. H. K. K.

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**CONTINUING DATA VERIFIED:

** FOREIGN APPLICATIONS VERIFIED:

PG-PUB	DO NOT PUBLISH <input checked="" type="checkbox"/>	RESCIND <input type="checkbox"/>
Foreign priority claimed <input type="checkbox"/> yes <input type="checkbox"/> no 35 USC 119 conditions met <input type="checkbox"/> yes <input type="checkbox"/> no Verified and Acknowledged Examiners's initials		ATTORNEY DOCKET NO TS01-603
TITLE : Photoresist scum for copper dual damascene process		

U.S. DEPT. OF COMM. / PAT. & TM-PTO-436L (Rev. 12-94)

NOTICE OF ALLOWANCE MAILED		CLAIMS ALLOWED	
		Total Claims	Print Claim for O.G.
Assistant Examiner		DRAWING	
Amount Due Date Paid		Sheets Drawg.	Figs. Drawg.
<input type="checkbox"/> TERMINAL DISCLAIMER		Print Fig.	
PREPARED FOR ISSUE		Application Examiner	
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